

# HOSTAFORM® C 2521 XAP®2

## HOSTAFORM®

POM copolymer Stiff-flowing type for injection molding and extrusion with high impact toughness and good tracking resistance over a high range of temperature; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. With reduced emissions especially for automotive interior application. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Emission according to VDA 275 < 5 mg/kg.

### Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

### Rheological properties

Melt volume-flow rate	2.5 cm <sup>3</sup> /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

### Typical mechanical properties

Tensile modulus	2450 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	62 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9 %	ISO 527-1/-2
Nominal strain at break	35 %	ISO 527-1/-2
Charpy impact strength, 23°C	250 <sup>[P]</sup> kJ/m <sup>2</sup>	ISO 179/1eU
Charpy impact strength, -30°C	250 kJ/m <sup>2</sup>	ISO 179/1eU
Charpy notched impact strength, 23°C	8.5 kJ/m <sup>2</sup>	ISO 179/1eA
Charpy notched impact strength, -30°C	7 kJ/m <sup>2</sup>	ISO 179/1eA
Poisson's ratio	0.38 <sup>[C]</sup>	

[P]: Partial Break

[C]: Calculated

### Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	101 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	120 E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155 W/(m K)	ISO 22007-2
Specific heat capacity of melt	2210 J/(kg K)	ISO 22007-4

### Flammability

Burning rate, Thickness 1 mm	41 mm/min	ISO 3795 (FMVSS 302)
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### Electrical properties

Relative permittivity, 100Hz	4	IEC 62631-2-1
Relative permittivity, 1MHz	4	IEC 62631-2-1
Dissipation factor, 100Hz	15 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50 E-4	IEC 62631-2-1
Volume resistivity	1E12 Ohm.m	IEC 62631-3-1

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Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	35 kV/mm	IEC 60243-1
Comparative tracking index	600	IEC 60112

### Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m³	ISO 1183

### Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa
Ejection temperature	140 °C

### Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low emissions

### Additional information

Injection molding

### Preprocessing

To achieve low emission values pre drying using a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

### Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

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### Postprocessing

Conditioning e.g. moisturizing is not necessary.

#### Processing Notes

### Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

### Storage

The product can then be stored in standard conditions until processed.

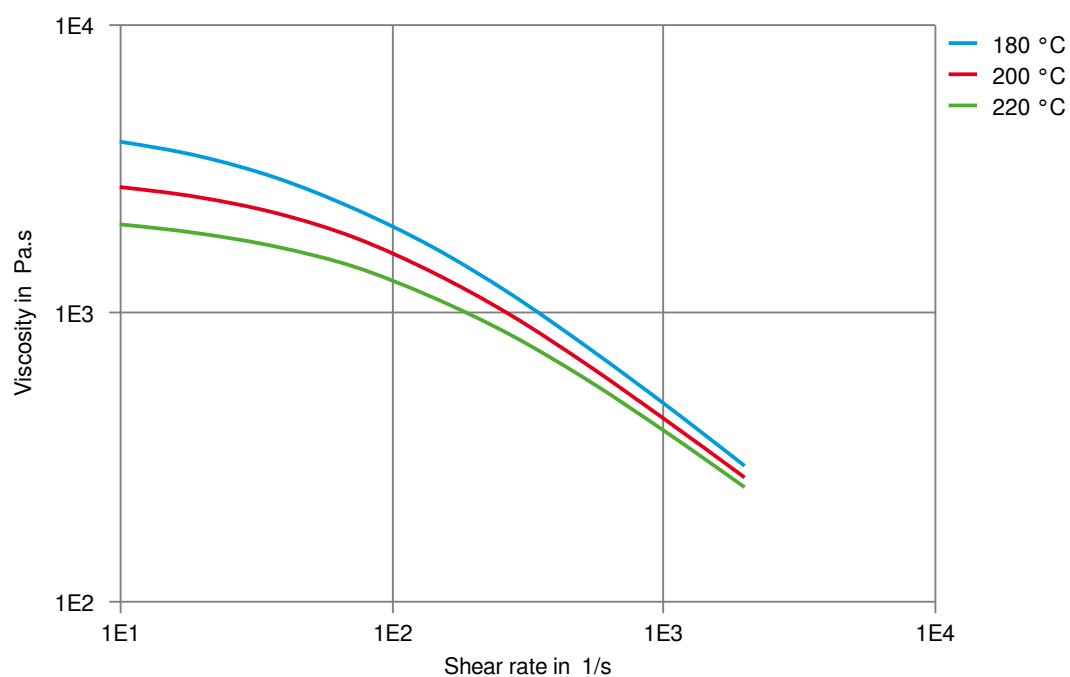
### Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Ford	WSK-M4D635-A1	
Li Auto	Q/LiA5310020	2021 (V2)
Mercedes-Benz	DBL5404	BQF
Mercedes-Benz	DBL5410	
Renault	No Spec, Special Part Approval, See Your CE Account Manager.	
VW Group	TL 524 76	Natural

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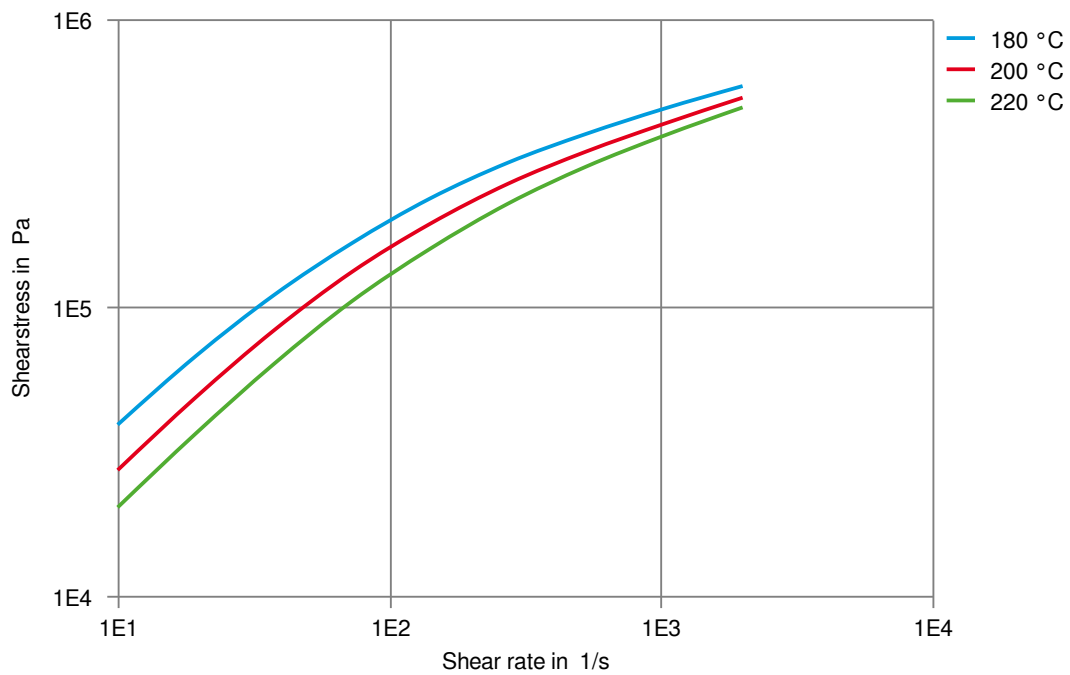
### Viscosity-shear rate



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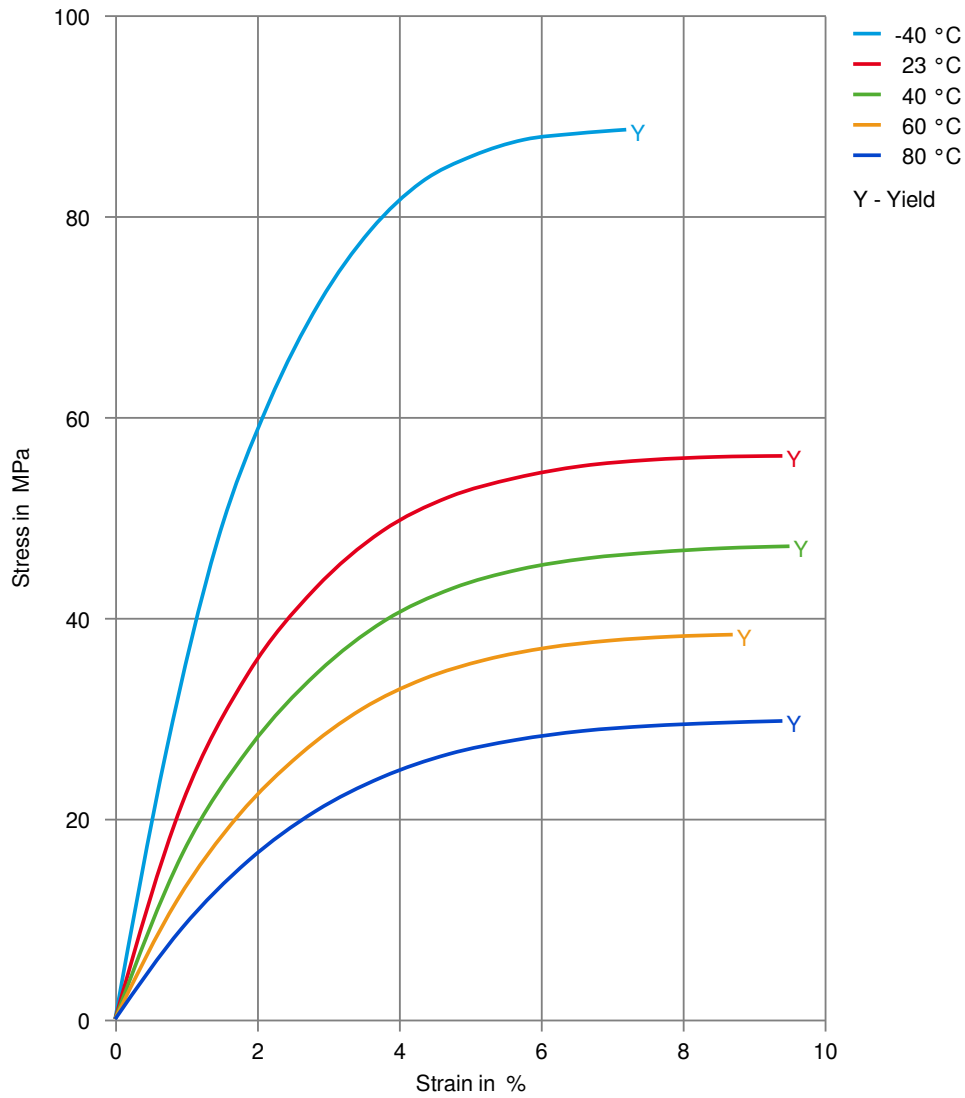
### Shearstress-shear rate



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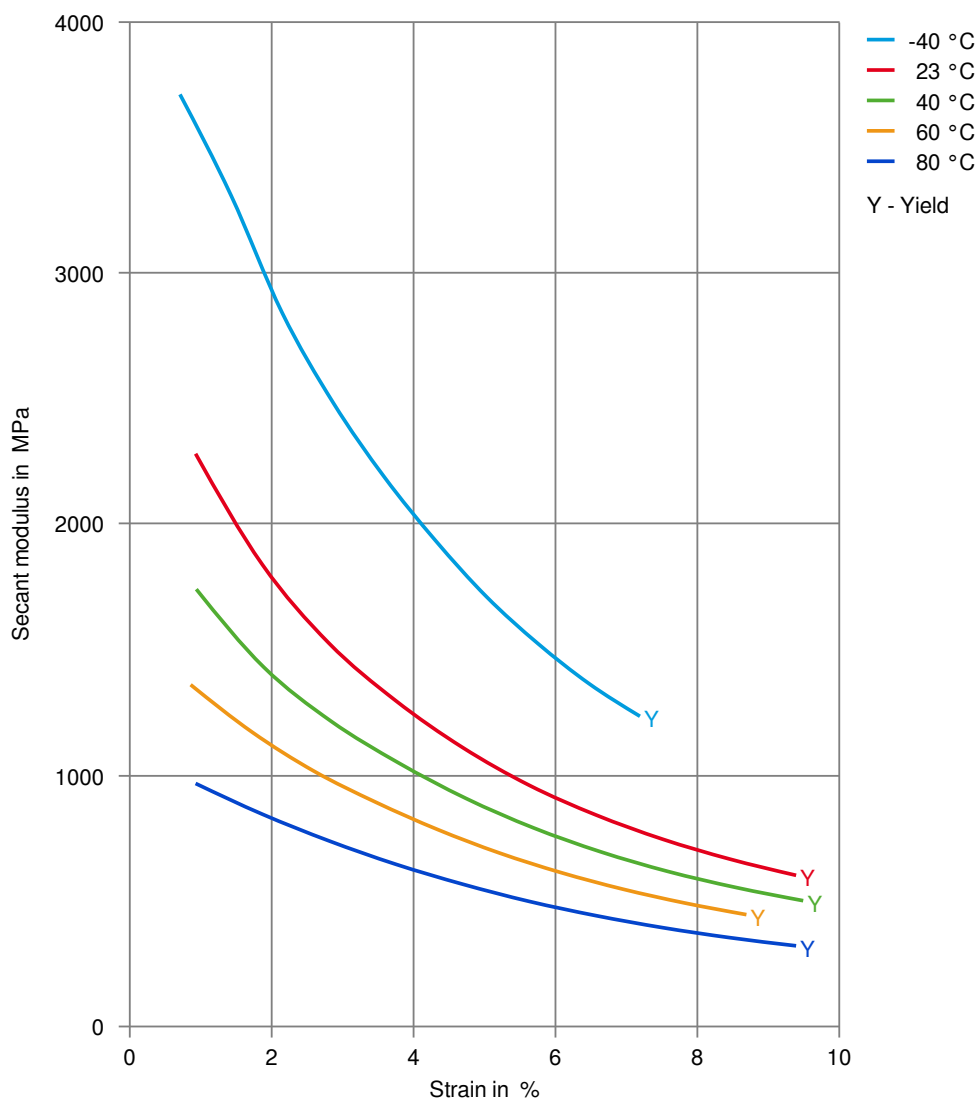
### Stress-strain



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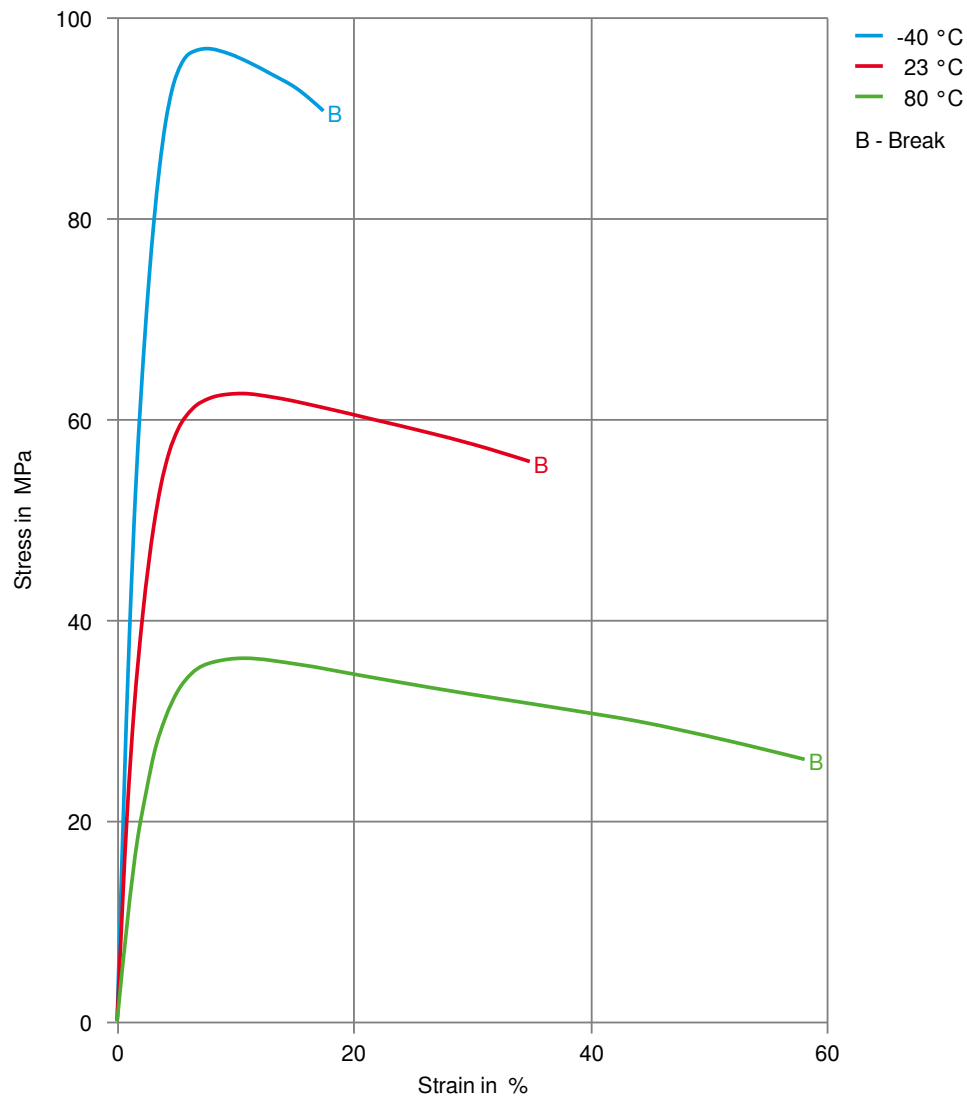
### Secant modulus-strain



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Stress-strain, 50mm/min

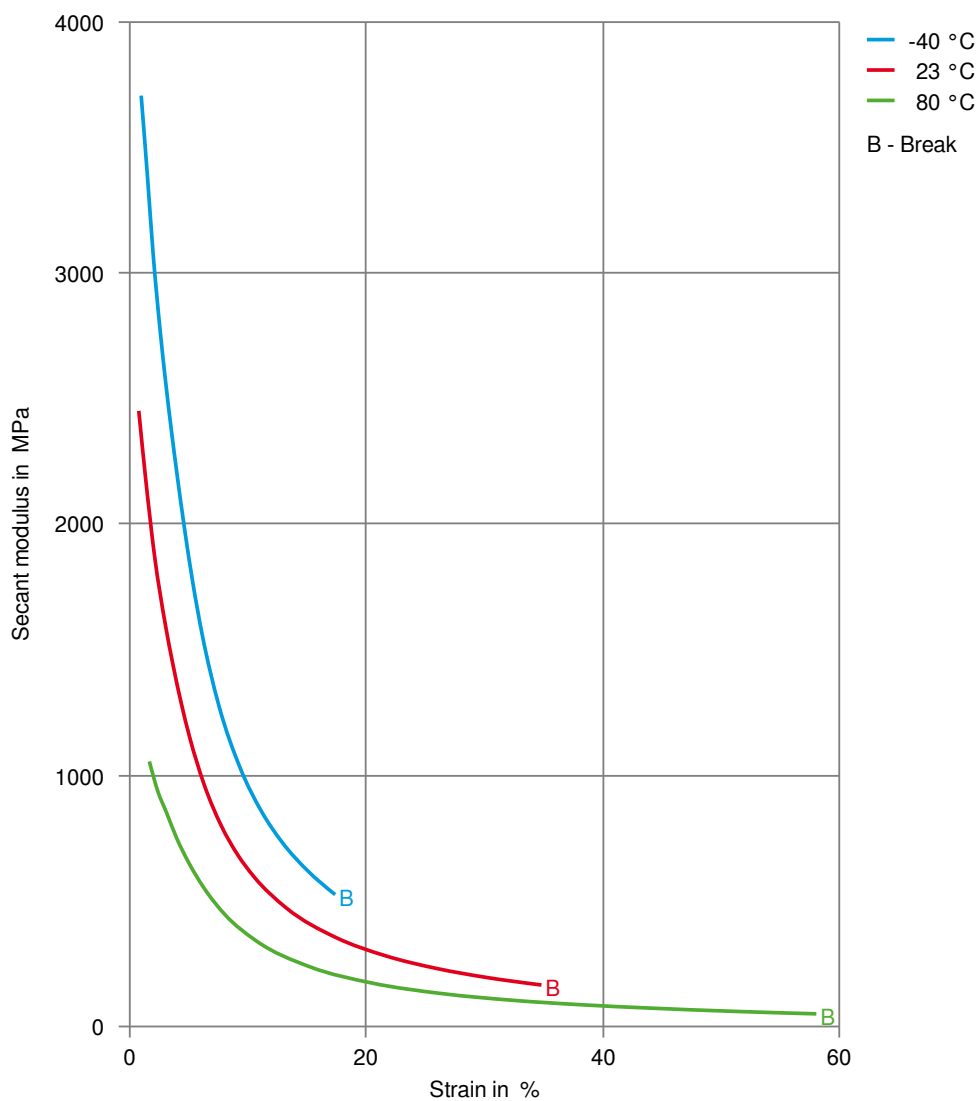




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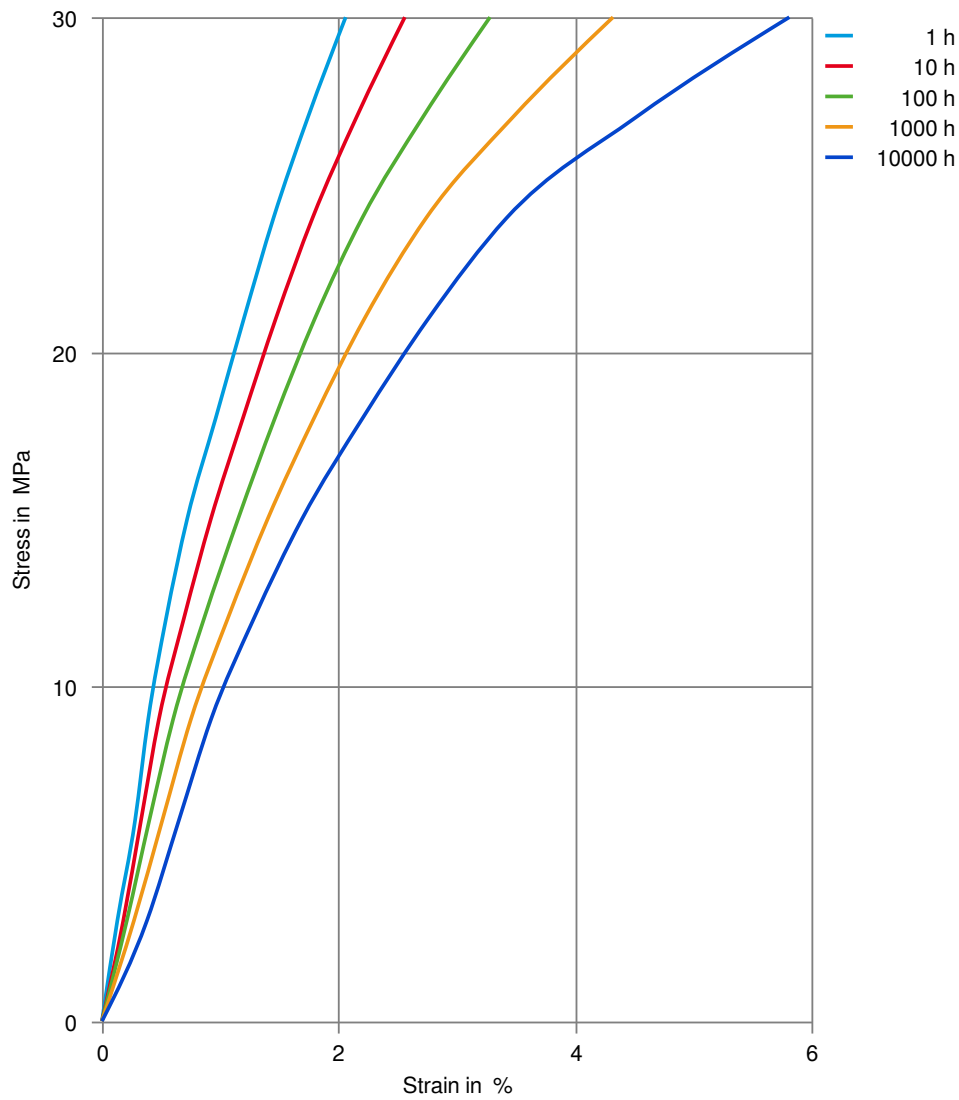
Secant modulus-strain, 50mm/min



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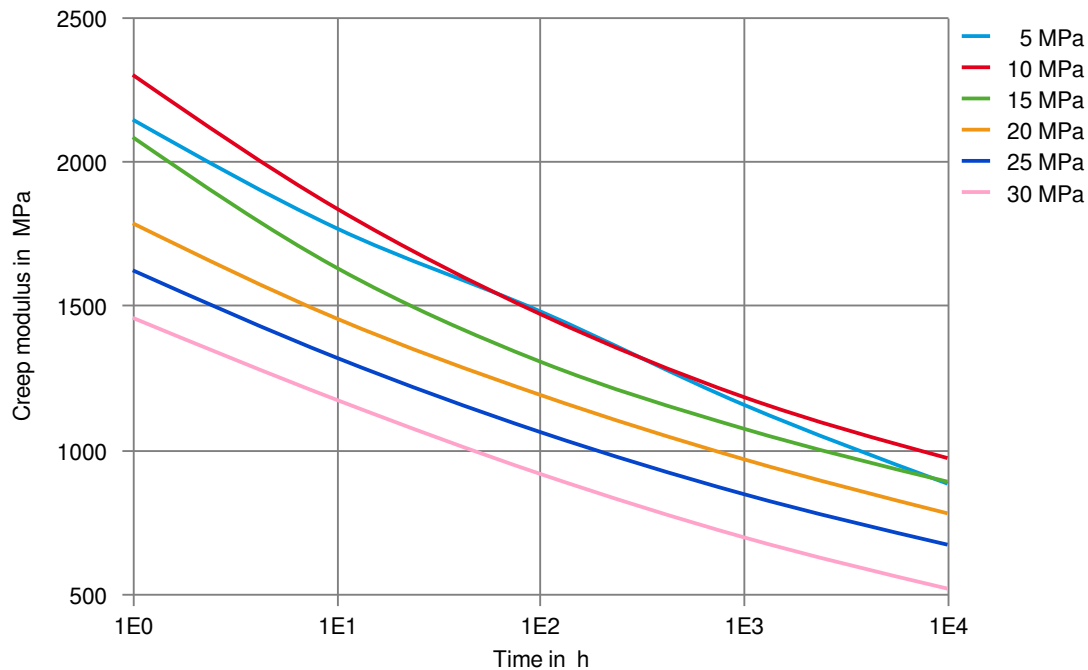
### Stress-strain (isochronous) 23°C



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### Creep modulus-time 23°C



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